

METHOD AND APPARATUS FOR DELIVERING  
POWER TO HIGH PERFORMANCE ELECTRONIC ASSEMBLIES

ABSTRACT OF THE DISCLOSURE

- 5 A method, apparatus, and article of manufacture for providing power from a first circuit board having a first circuit board first conductive surface and a first circuit board second conductive surface to a second circuit board having a second circuit board first conductive surface and a second circuit board second conductive surface is described. The apparatus comprises a first conductive member, including a first end having a first
- 10 conductive member surface electrically coupleable to the first circuit board first conductive surface and a second end distal from the first end having a first conductive member second surface electrically coupleable to the second circuit board first surface. The apparatus also comprises a second conductive member, having a second conductive member first surface electrically coupleable to the first circuit board second surface and a
- 15 second conductive member second surface distal from the second conductive member first surface electrically coupleable to the second circuit board second conductive surface.

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